

## ET1812A

### End Termination

#### Description

ET1812A is a solderable Ag/Pt end termination designed for use on NPO MLCC (multilayer ceramic chip capacitors). It offers excellent solderability and adhesion. ET1812A is supplied at a viscosity suitable for machine dip and blot or no blot applications

#### Key Features

- Suitable rheology for machine dip application Excellent solderability and adhesion Compatible on NPO dielectrics



*This picture does not show the packaging of ET1812A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Typical Properties

Viscosity	35 – 45 Kcps Brookfield RVTSC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C
Metal	AgPt

#### Recommended Processing Guide

Process Temperature (TDS)	780 – 810 °C peak temperature Dwell time of 5 – 6 minutes at peak
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Version (last updated) 26 Feb 2026